

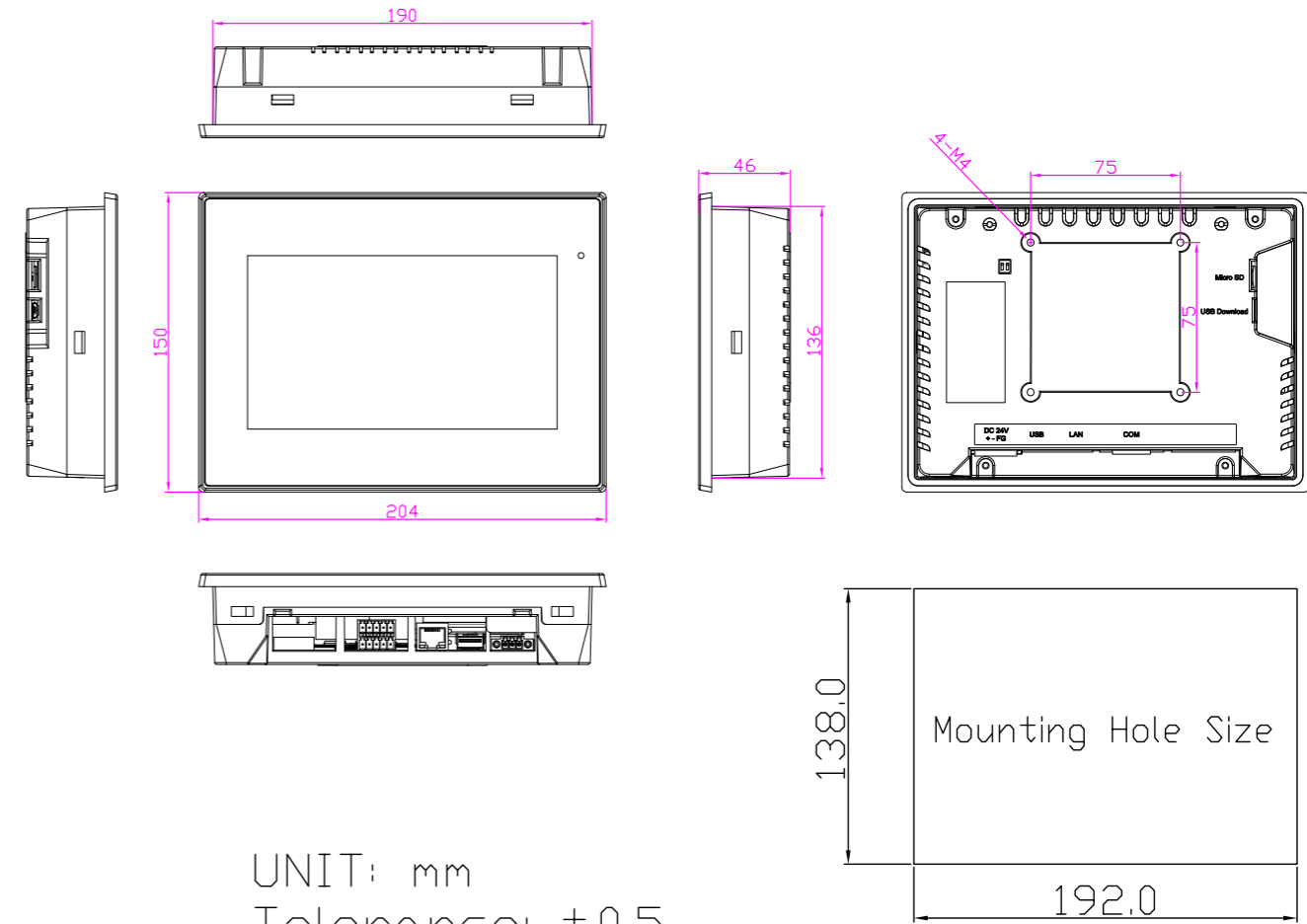
Features

- 7" Fanless Design ARM Based HMI
- Rugged Designed for Industrial Usage
- Flat Front Panel Designe
- Powerful Qual Core ARM Cortex-A72 Processors
- Onboard 4GB LPDDR4 Memory
- Onboard 16GB/32GB eMMC Flash
- DC 24V Power Input With 3kV Power Isolation

Specifications

System	
Processor	Broadcom BCM2711, ARM Cortex-A72 (4x Cores, up to 1.5GHz)
System Chipset	NA
Memory	Onboard DDR4 4GB SDRAM
External IO Port	
USB	2 x USB 2.0 type A 1 x USB Download Mode, Micro USB
Serial / Parallel	1 x 2 x 5pin External Terminal Block with 2 x COM 1 x RS232(TX, RX, RTS, CTS) / 485 1 x RS232(TX, RX, RTS, CTS)
LAN	1 x GbE LAN, RJ45
Wi-Fi+Bluetooth (optional)	Onboard Wi-Fi/ Bluetooth module • 2.4 GHz, 5.0 GHz IEEE 802.11 b/g/n/ac wireless • Bluetooth 5.0, BLE.
Storage Space	
Storage	16GB/32GB eMMC Flash
Expansion	
Expansion Slot	1 x Half / Full-size mPCIe slot with micro SIM slot
Expansion Daughter Boards	Support TB-508 series expansion boards
Display	
Display Type	7" TFT-LCD
Max. Resolution	800 x 480
Max. Color	262K
Luminance (cd/m ²)	400
View Angle	140(H)/120(V)
Contrast	500:1
Backlight Lifetime	20,000 hrs
Touch Screen	
Type	Projected Capacitive Touch
Interface	USB
Light Transmission(%)	Over 85%
Power	
Power Input	DC 24V
Power Isolation	3kV
Power Consumption	7.7W

Dimensions



Mechanical	
Construction	Industrial Plastic Chassis
Mounting	Panel Mount, VESA 75 x 75
IP Rating	IP65 compliant front bezel
Dimensions	204 x 150 x 46 mm
Net Weight	0.7 kg
Environmental	
Operating Temperature	0~50°C/ -20~60°C (option)
Storage Temperature	-30~70°C
Humidity	10 to 95% @ 40°C, non- condensing
Certificate	CE/FCC Class A
Operating System Support	
Android 10 (Default) / Yocto Linux	
Ordering Information	
ARMPAC-607BP	7" 800x480 fanless HMI barebone with Broadcom BCM2711 quad core ARM Cortex-A72,4GB LPDDR4 ,16/32GB eMMC,PCAP touch, 24V DC input with 3kV isolated, plastic chassis.